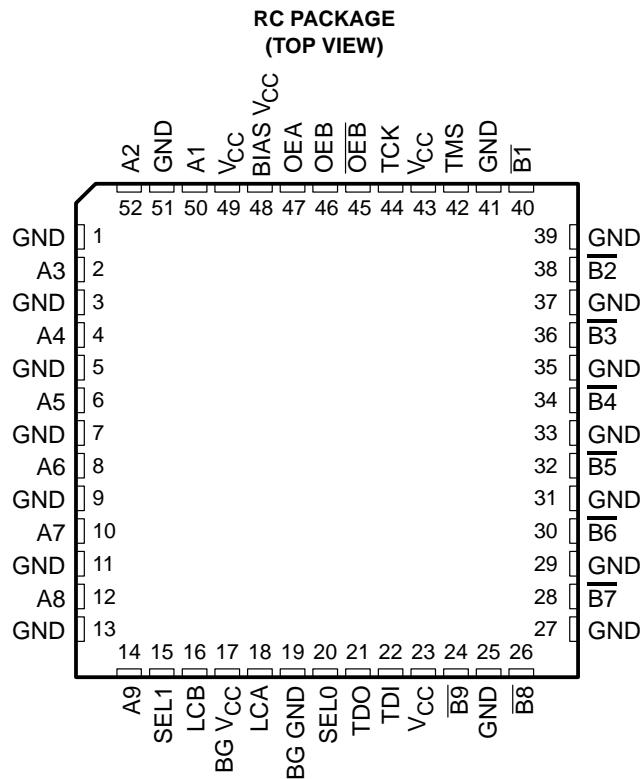


- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) \bar{B} Port
- Open-Collector \bar{B} -Port Outputs Sink 100 mA
- High-Impedance State During Power Up and Power Down
- BIAS V_{CC} Minimizes Signal Distortion During Live Insertion or Withdrawal
- \bar{B} -Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping to Aid in Line Termination



description

The SN74FB2031 is a 9-bit transceiver designed to translate signals between TTL and backplane transceiver logic (BTL) environments. The device is designed specifically to be compatible with IEEE Std 1194.1-1991.

The \bar{B} port operates at BTL-signal levels. The open-collector \bar{B} ports are specified to sink 100 mA. Two output enables (OEB and \bar{OEB}) are provided for the \bar{B} outputs. When OEB is low, \bar{OEB} is high, or V_{CC} is less than 2.1 V, the \bar{B} port is turned off.

The A port operates at TTL signal levels. The A outputs reflect the inverse of the data at the \bar{B} port when the A-port output enable (OEA) is high. When OEA is low or V_{CC} is less than 2.1 V, the A outputs are in the high-impedance state.

Pins are allocated for the four-wire IEEE Std 1149.1 (JTAG) test bus, although currently there are no plans to release a JTAG-featured version. TMS and TCK are not connected and TDI is shorted to TDO.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74FB2031

9-BIT TTL/BTL ADDRESS/DATA TRANSCEIVER

SCBS176N – NOVEMBER 1991 – REVISED JUNE 2001

description (continued)

BIAS V_{CC} establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when V_{CC} is not connected.

BG V_{CC} and BG GND are the supply inputs for the bias generator.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	QFP – RC	Tube	SN74FB2031RC	FB2031

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

TRANSCEIVER

INPUTS			FUNCTION
OEA	OEB	OEB	
L	H	L	\bar{A} data to B bus
H	L	X	\bar{B} data to A bus
H	X	H	
H	H	L	\bar{A} data to B bus, \bar{B} data to A bus
L	L	X	
L	X	H	Isolation

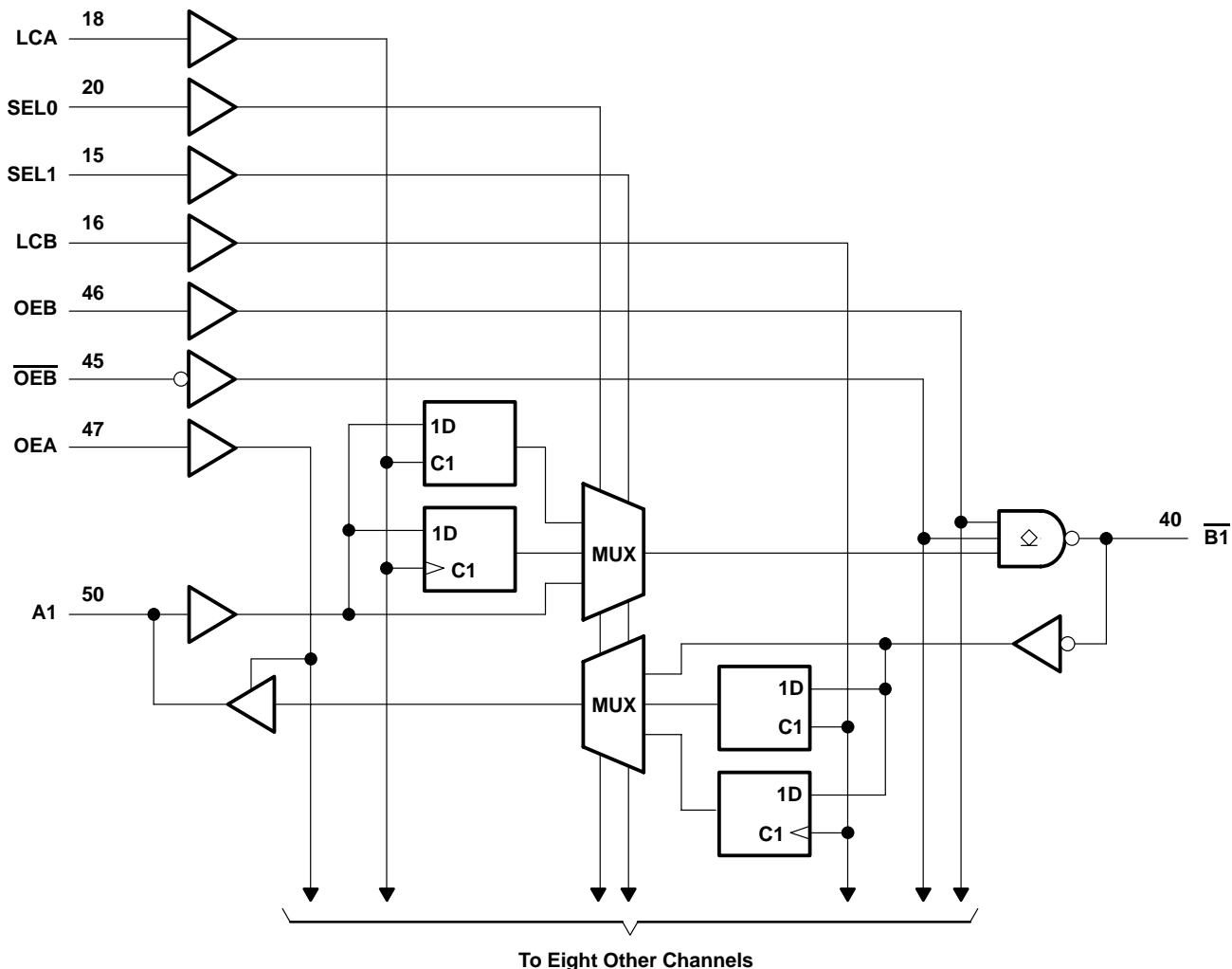
STORAGE MODE

LCA, LCB	RESULT
0	Transparent
1	Latches latched
↑	Flip-flops triggered

SELECT

SEL1	SEL0	MUX A→B	MUX B→A
0	0	Latch	Latch
0	1	Through	Through
1	0	Flip-flop	Flip-flop
1	1	Flip-flop	Latch

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I : Except \bar{B} port	-1.2 V to 7 V
\bar{B} port	-1.2 V to 3.5 V
Voltage range applied to any \bar{B} output in the disabled or power-off state, V_O	-0.5 V to 3.5 V
Voltage range applied to any output in the high state, V_O	-0.5 V to V_{CC}
Input clamp current, I_{IK} : Except \bar{B} port	-40 mA
\bar{B} port	-18 mA
Current applied to any single output in the low state, I_O : A port	48 mA
\bar{B} port	200 mA
Package thermal impedance, θ_{JA} (see Note 1)	44°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V_{CC} , BIAS V_{CC} , BG V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage	\bar{B} port	1.62	2.3		V
		Except \bar{B} port	2			
V_{IL}	Low-level input voltage	\bar{B} port	0.75	1.47		V
		Except \bar{B} port		0.8		
I_{OH}	High-level output current	A port		-3	mA	
I_{OL}	Low-level output current	A port		24		mA
		\bar{B} port		100		
T_A	Operating free-air temperature		0	70	$^{\circ}$ C	

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V_{CC} (5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{IK}	\bar{B} port	$V_{CC} = 4.5$ V, $I_I = -18$ mA		-1.2		V
	Except \bar{B} port	$V_{CC} = 4.5$ V, $I_I = -40$ mA		-0.5		
V_{OH}	A port	$V_{CC} = 4.5$ V, $I_{OH} = -3$ mA	2.5	3.3		V
V_{OL}	A port	$V_{CC} = 4.5$ V, $I_{OL} = 24$ mA		0.35	0.5	V
	\bar{B} port	$V_{CC} = 4.5$ V	$I_{OL} = 80$ mA	0.75	1.1	
			$I_{OL} = 100$ mA		1.15	
I_I	Except \bar{B} port	$V_{CC} = 5.5$ V, $V_I = 5.5$ V		50	μ A	
I_{IH}^{\ddagger}	Except \bar{B} port	$V_{CC} = 5.5$ V, $V_I = 2.7$ V		50	μ A	
I_{IL}^{\ddagger}	Except \bar{B} port	$V_{CC} = 5.5$ V, $V_I = 0.5$ V		-50		μ A
	\bar{B} port	$V_{CC} = 5.5$ V, $V_I = 0.75$ V		-100		
I_{OZH}	A port	$V_{CC} = 2.1$ V to 5.5 V, $V_O = 2.7$ V		50	μ A	
I_{OZL}	A port	$V_{CC} = 2.1$ V to 5.5 V, $V_O = 0.5$ V		-50	μ A	
I_{OZPU}	A port	$V_{CC} = 0$ to 2.1 V, $V_O = 0.5$ V to 2.7 V		50	μ A	
I_{OZPD}	A port	$V_{CC} = 2.1$ V to 0, $V_O = 0.5$ V to 2.7 V		-50	μ A	
I_{OH}	\bar{B} port	$V_{CC} = 0$ to 5.5 V, $V_O = 2.1$ V		100	μ A	
$I_{OS}^{\$}$	A port	$V_{CC} = 5.5$ V, $V_O = 0$	-30	-150	mA	
I_{CC}	A port to \bar{B} port	$V_{CC} = 5.5$ V, $I_O = 0$		78		mA
	\bar{B} port to A port			78		
C_i		$V_I = 0.5$ V or 2.5 V		4.5	pF	
C_{io}	A port	$V_O = 0.5$ V or 2.5 V		8.5		pF
	\bar{B} port per IEEE Std 1194.1-1991	$V_{CC} = 0$ to 5.5 V		6		

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C.

‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

live-insertion specifications over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT	
I _{CC} (BIAS V _{CC})	V _{CC} = 0 to 4.5 V	V _B = 0 to 2 V, V _I (BIAS V _{CC}) = 4.5 V to 5.5 V		450	10	μA	
	V _{CC} = 4.5 V to 5.5 V						
V _O	–B port	V _{CC} = 0, V _I (BIAS V _{CC}) = 5 V		1.62	2.1	V	
I _O	–B port	V _{CC} = 0, V _B = 1 V, V _I (BIAS V _{CC}) = 4.5 V to 5.5 V		–1		μA	
		V _{CC} = 0 to 5.5 V, OEB = 0 to 0.8 V		100			
		V _{CC} = 0 to 2.2 V, OEB = 0 to 5 V		100			

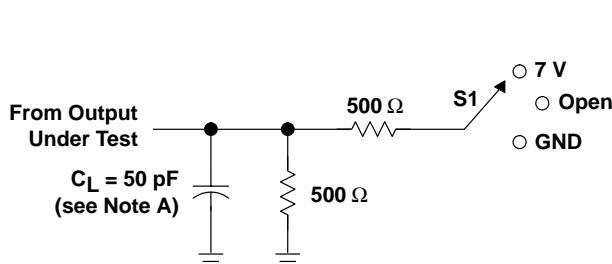
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
f _{clock}	Clock frequency			150	MHz
t _w	Pulse duration	LCA or LCB	3.3		ns
t _{su}	Setup time	Clock mode	Data before LCA↑	1.4	ns
			Data before LCB↑	2.8	
		Latch mode	Data before LCA↑	1.1	
			Data before LCB↑	2.4	
t _h	Hold time	Clock mode	Data after LCA↑	0.6	ns
			Data after LCB↑	0	
		Latch mode	Data after LCA↑	0.9	
			Data after LCB↑	0	

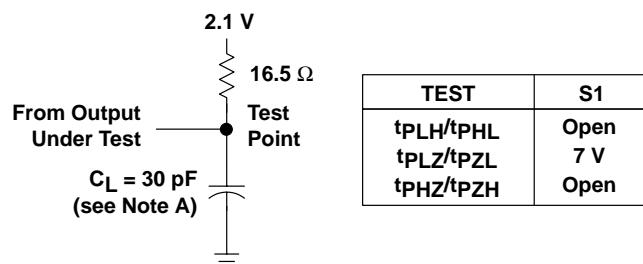
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			150			150		MHz
t _{PLH}	A (through mode)	B̄	3.7	4.5	5.9	3.2	6.6	ns
t _{PHL}			2.9	4	5.7	2.6	5.9	
t _{PLH}	A (transparent)	B̄	4.1	5	6.5	3.6	7.3	ns
t _{PHL}			3.3	4.5	6.1	3	6.5	
t _{PLH}	LCA	B̄	4.5	5.4	7	3.9	7.8	ns
t _{PHL}			4	5.1	6.7	3.4	7.4	
t _{PLH}	LCB	A	2.8	3.7	4.7	1.9	6	ns
t _{PHL}			2.5	3.4	4.9	1.8	5.5	
t _{PLH}	SEL1 or SEL0	A	2.5	3.8	5.3	1.9	6.3	ns
t _{PHL}			2.2	3.5	5.1	1.6	5.6	
t _{PLH}	SEL1 or SEL0	B̄	4.1	5.3	6.9	3.7	7.8	ns
t _{PHL}			3.7	5.2	6.9	3.3	7.7	
t _{PLH}	B̄ (through mode)	A	3.1	4	5.6	2.2	7.1	ns
t _{PHL}			2.6	3.4	4.9	1.4	5.7	
t _{PLH}	B̄ (transparent)	A	3.3	4.2	5.9	2.4	7.6	ns
t _{PHL}			2.8	3.9	5.5	1.8	6.3	
t _{PLH}	OEB or OEB̄	B̄	3.7	4.6	6.1	3.2	6.7	ns
t _{PHL}			2.9	4.3	5.8	2.5	6.4	
t _{PZH}	OEA	A	2.3	3.1	4.5	1.6	5	ns
t _{PZL}			1.9	2.7	4.1	1.6	4.4	
t _{PHZ}	OEA	A	2.2	3.1	4.5	1.5	5.2	ns
t _{PLZ}			2.5	3.3	4.9	2	5.2	
t _{sk(p)} Pulse skew	A	B̄	0.5					ns
	B̄	A	0.3					
t _{sk(o)} Output skew	A	B̄	0.2					ns
	B̄	A	0.3					
t _t	Transition time, B̄ outputs (1.3 V to 1.8 V)		0.6	2	2.8	0.4	2.9	ns
	Transition time, Ā outputs (10% to 90%)		0.5	3.5	4.7	0	5.4	
t _(pr)	B̄-port input pulse rejection		1			1		ns

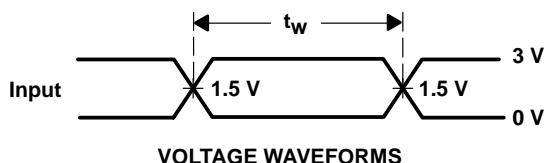
PARAMETER MEASUREMENT INFORMATION



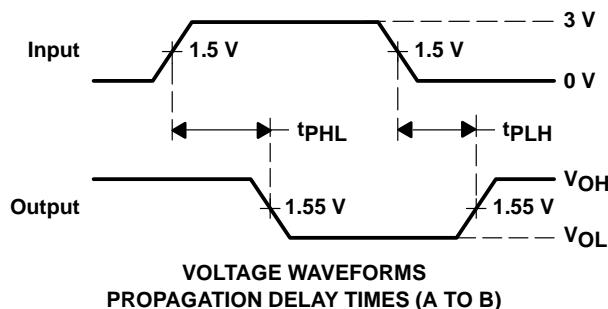
LOAD CIRCUIT FOR A OUTPUTS



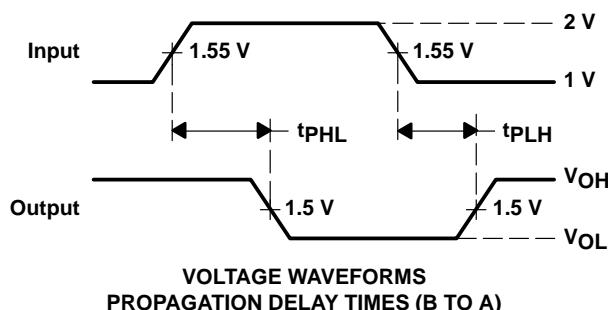
LOAD CIRCUIT FOR B OUTPUTS



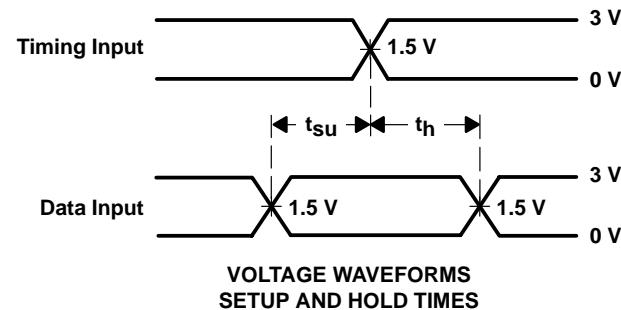
VOLTAGE WAVEFORMS
PULSE DURATION



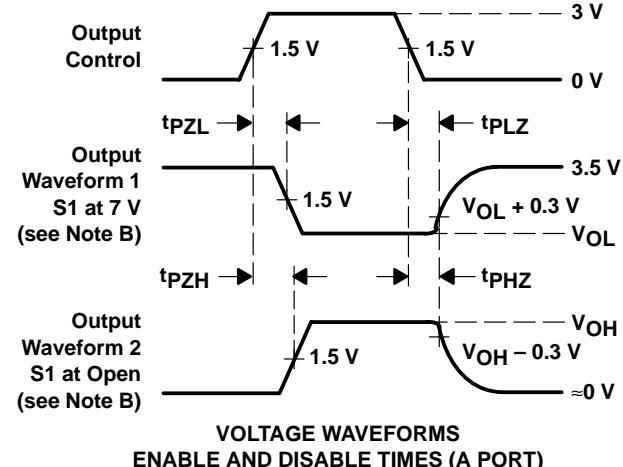
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (A TO B)



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (B TO A)



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES (A PORT)

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$; BTL inputs: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74FB2031RC	LIFEBUY	QFP	RC	52	96	TBD	CU SNPB	Level-2-240C-1 YEAR	0 to 70	FB2031	
SN74FB2031RCG3	ACTIVE	QFP	RC	52	96	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	0 to 70	FB2031	Samples
SN74FB2031RCR	LIFEBUY	QFP	RC	52	500	TBD	CU SNPB	Level-2-240C-1 YEAR	0 to 70	FB2031	
SN74FB2031RCRG3	ACTIVE	QFP	RC	52	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	0 to 70	FB2031	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN74FB2031 :



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PACKAGE OPTION ADDENDUM

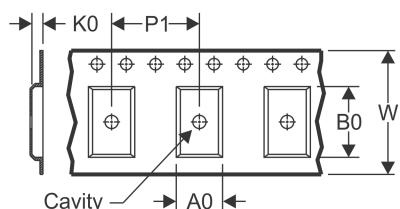
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- Military: [SN54FB2031](#)

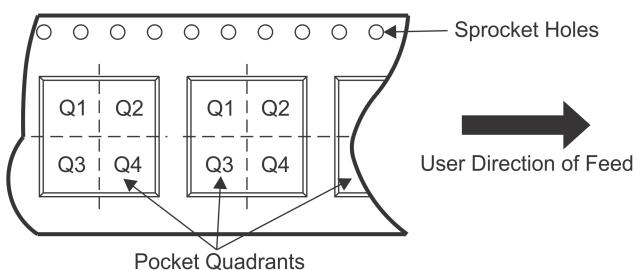
NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74FB2031RCR	QFP	RC	52	500	330.0	24.4	14.2	14.2	2.6	24.0	24.0	Q2
SN74FB2031RCRG3	QFP	RC	52	500	330.0	24.4	14.2	14.2	2.6	24.0	24.0	Q2

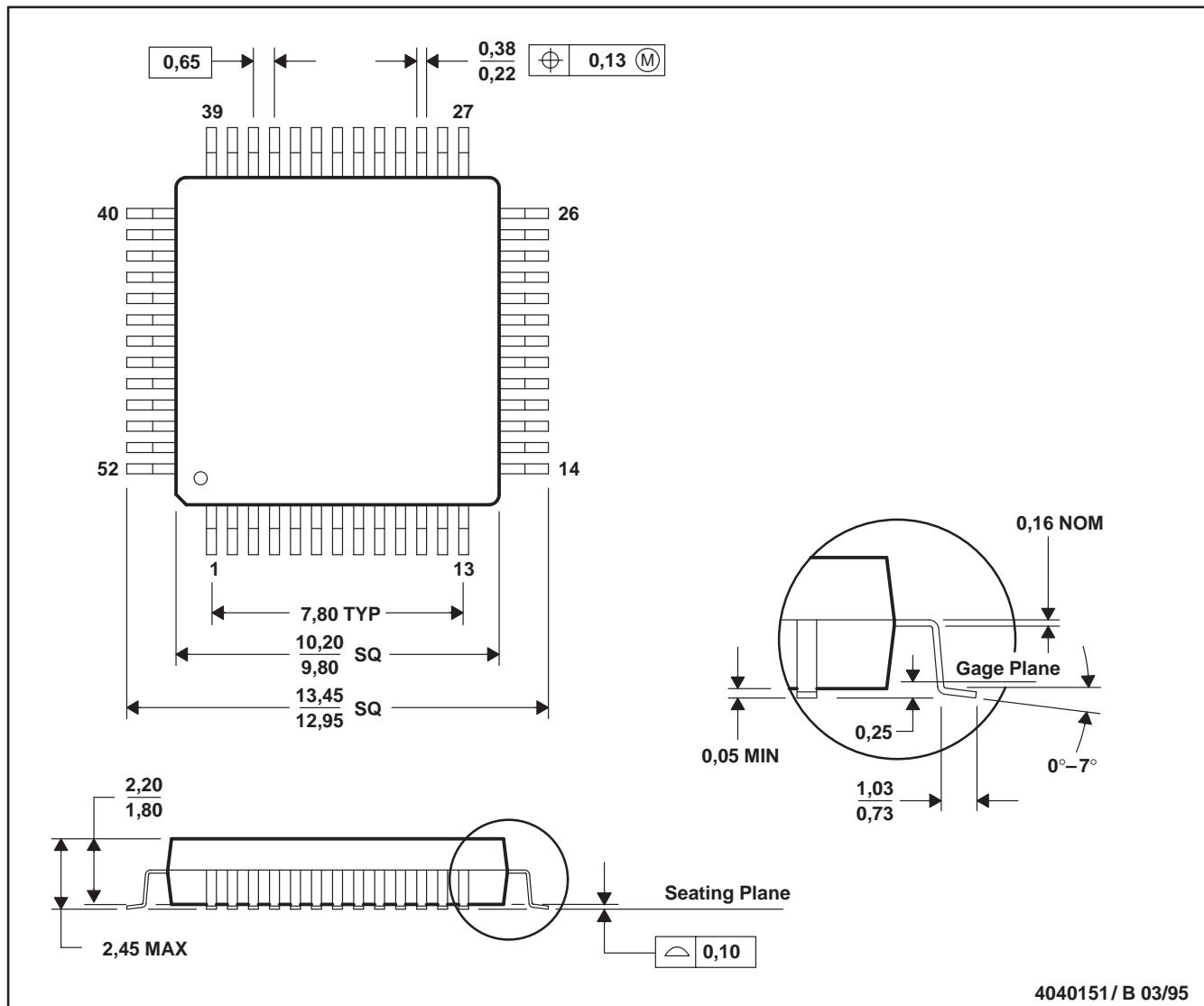
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74FB2031RCR	QFP	RC	52	500	367.0	367.0	45.0
SN74FB2031RCRG3	QFP	RC	52	500	367.0	367.0	45.0

RC (S-PQFP-G52)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-022

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